

FIG. 1
(PRIOR ART)

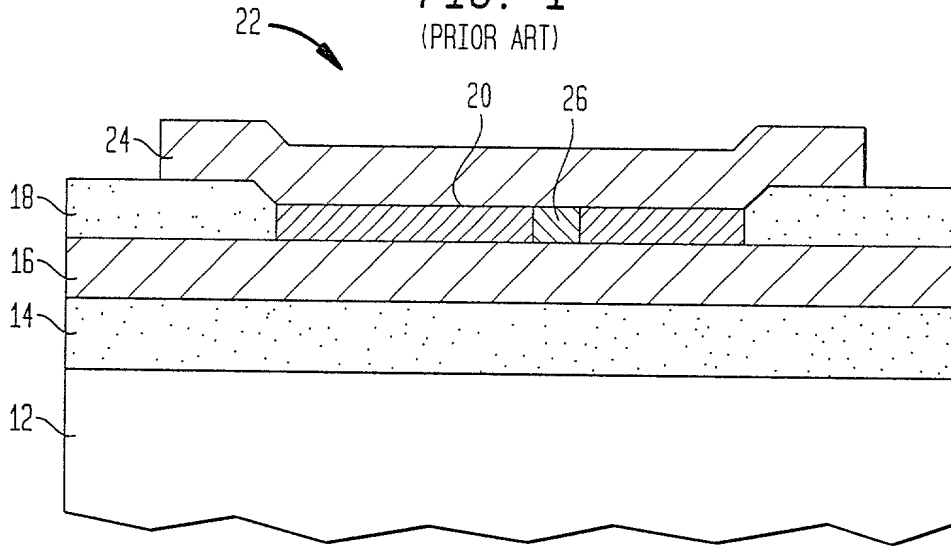


FIG. 2a

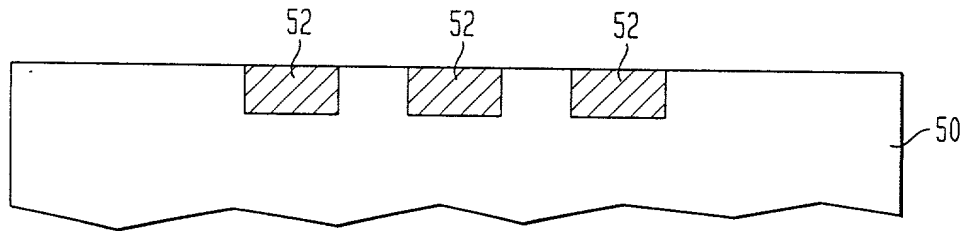


FIG. 2b

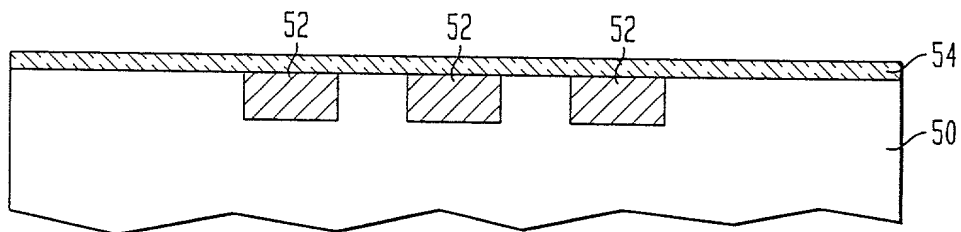


FIG. 2c

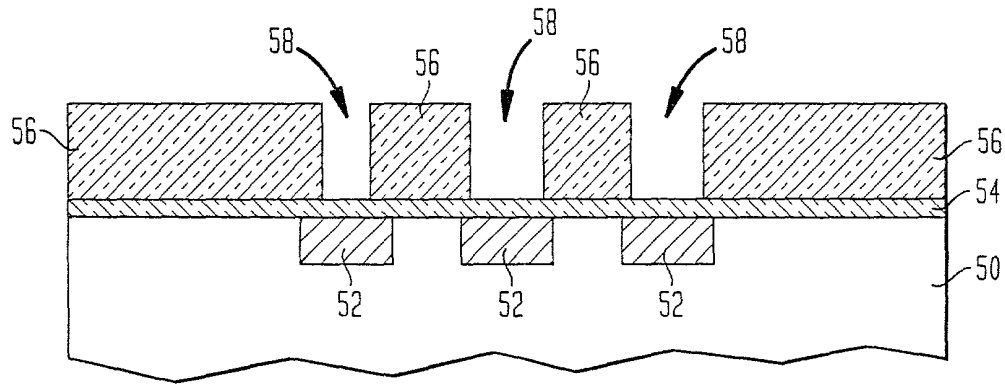


FIG. 2d

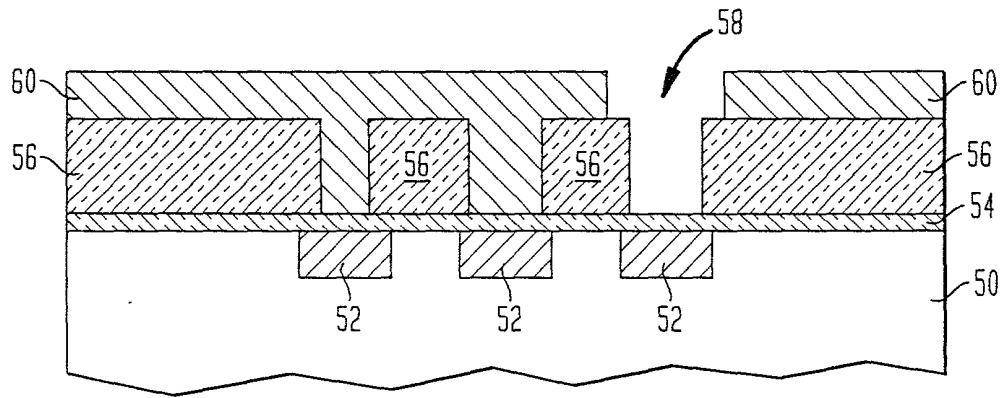


FIG. 2e

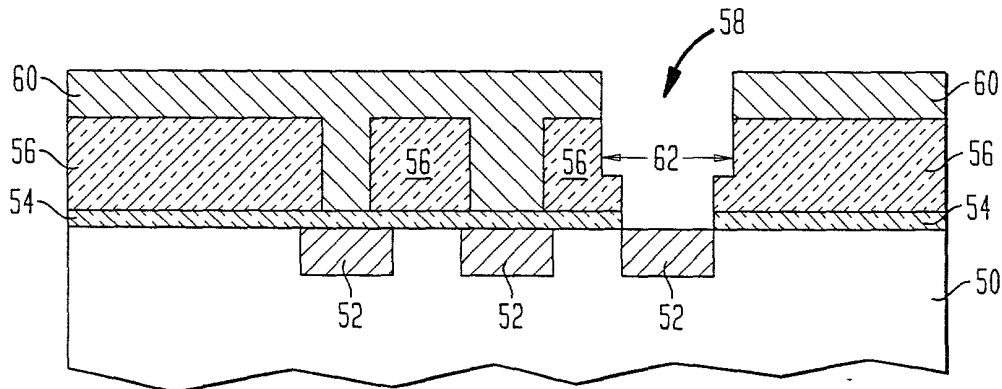


FIG. 2f

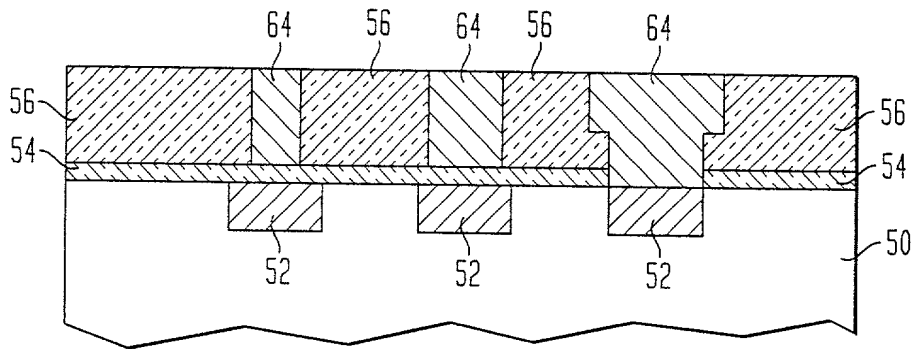


FIG. 3

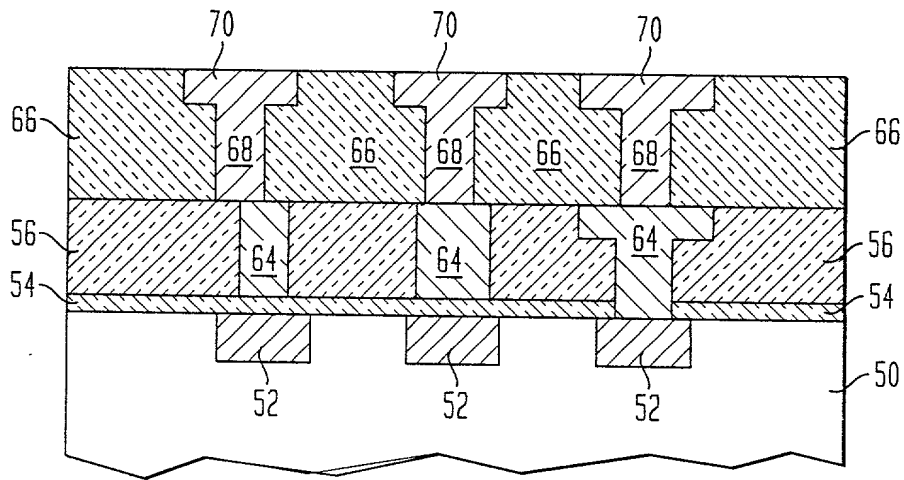
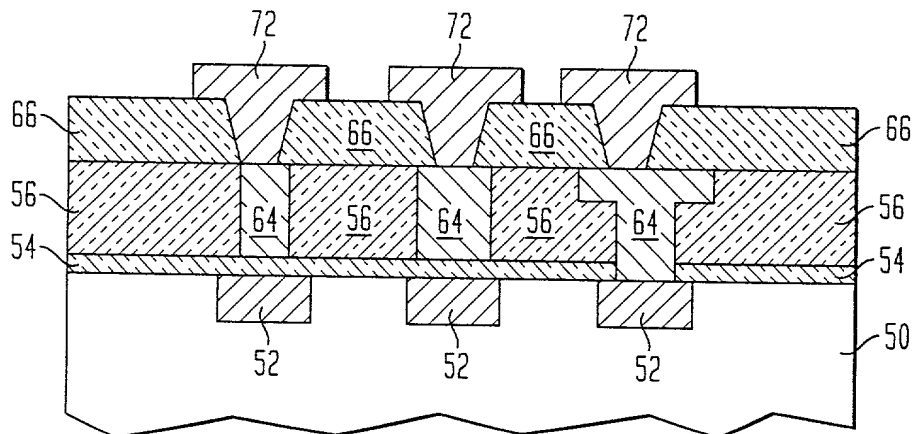


FIG. 4



This cross-sectional view shows a substrate 50 with a trench 52. A layer 54 is deposited on the substrate, and a layer 56 is deposited on top of layer 54. A trench 56 is formed in layer 56, and a layer 59 is deposited in the trench. A layer 62 is deposited on top of layer 56, and a layer 64 is deposited in the trench. The trench 56 is filled with a material 56, and the layer 59 is a conductive layer. The layer 62 is a dielectric layer, and the layer 64 is a conductive layer. The trench 56 is formed in layer 56, and the layer 59 is deposited in the trench. The layer 62 is deposited on top of layer 56, and the layer 64 is deposited in the trench. The trench 56 is filled with a material 56, and the layer 59 is a conductive layer. The layer 62 is a dielectric layer, and the layer 64 is a conductive layer.